

40V N-Channel Trench MOSFET(Preliminary)

General Description			Product Summary		
 Trench Power technology Low R_{DS(ON)} Low Gate Charge Optimized for fast-switching applications 			V_{DS} $I_{D} (at V_{GS} = 10V)$ $R_{DS(ON)} (at V_{GS} = 10V)$ $R_{DS(ON)} (at V_{GS} = 4.5V)$	40V 20A <23mΩ <28mΩ	
 Applications Synchronous Rectification in DC/DC and AC/DC Converters Isolated DC/DC Converters in Telecom and Industrial 			100% UIS Tested	RoHS	
	TO-252 G D S	D			
Part Number	Packa	де Туре	Form	Marking	
TTD20N04AT	то	-252	Tape&Reel	TTD20N04AT	
Absolute Maximum Ra	tings (T -2				
Parameter		Symbol	therwise noted) Maximum	Units	
Parameter		1		Units V	
Parameter Drain-Source Voltage	ungs (1 _A –23	Symbol	Maximum		
Parameter Drain-Source Voltage Gate-Source Voltage	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS}	Maximum 40	V	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current ^B	T _c =25°C	Symbol V _{DS} V _{GS}	Maximum 40 ±20 20	V V	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current	T _c =25°C	Symbol V _{DS} V _{GS} I _D	Maximum 40 ±20 20 17	V V A	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current	T _c =25°C	Symbol V _{DS} V _{GS} I _D I _{DM}	Maximum 40 ±20 20 17 60	V V A A	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS}	Maximum 40 ±20 20 17 60 13	V V A A A A	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ L = 0.3mH ^A	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS}	Maximum 40 ±20 20 17 60 13 25	V V A A A M mJ	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS}	Maximum 40 ±20 20 17 60 13 25 28.8	V V A A A M M W	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C Junction and Storage Temperatu	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D	Maximum 40 ±20 20 17 60 13 25 28.8 14.4	V V A A A M M W W	
Parameter Drain-Source Voltage Gate-Source Voltage	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D	Maximum 40 ±20 20 17 60 13 25 28.8 14.4	V V A A A M M W W	
Parameter Drain-Source Voltage Gate-Source Voltage Continuous Drain Current B Pulsed Drain Current Avalanche Current A Single Pulse Avalanche Energy Power Dissipation C Junction and Storage Temperatu Thermal Characteristics	$T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$ $L = 0.3mH^{A}$ $T_{c} = 25^{\circ}C$ $T_{c} = 100^{\circ}C$	Symbol V _{DS} V _{GS} I _D I _{DM} I _{AS} E _{AS} P _D T _J , T _{STG}	Maximum 40 ±20 20 17 60 13 25 28.8 14.4 -55 to 175	V V A A A M A M W W W W	



Electric	cal Characteristics(T _J =25°C ur	less otherwise r	noted)				
Symphol	Deremeter	Conditions		Value			
Symbol	Parameter			Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I _D =250µA,V _{GS} =0V		40			V
I _{DSS} Zer	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	T _J =25°C			1	μA
			T _J =125°C			100	
I _{GSS}	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	1			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA		1	1.4	2	V
		V _{GS} =10V, I _D =20A			18	23	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =16A			21.5	28	mΩ
9 _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A			19		S
V _{SD}	Diode Forward Voltage	I _S =20A, V _{GS} =0V				1	V
l _s	Maximum Body-Diode Continuous Curre	rent ^B				20	Α
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =20V, f =1MH _Z			659		pF
C _{oss}	Output Capacitance				70		
C _{rss}	Reverse Transfer Capacitance				62		
R _g	Gate Resistance	f =1MH _z			1.2		Ω
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V,V _{DS} =20V, I _D =20A			16.7		
Q _g (4.5V)	Total Gate Charge				9		nC
Q _{gs}	Gate Source Charge				1.9		
Q_{gd}	Gate Drain Charge				4.5		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 20A, R_{G} = 1.8\Omega$			31		
t _r	Turn-On Rise Time				3.6		ns
T _{D(off)}	Turn-Off Delay Time				46		
t _f	Turn-Off Fall Time				2.8		
t _{rr}	Body Diode Reverse Recovery Time		16		18.3		ns
Q _{rr}	Body Diode Reverse Recovery Charge	−−I _F =20A, di/dt =100A/µs			4		nC

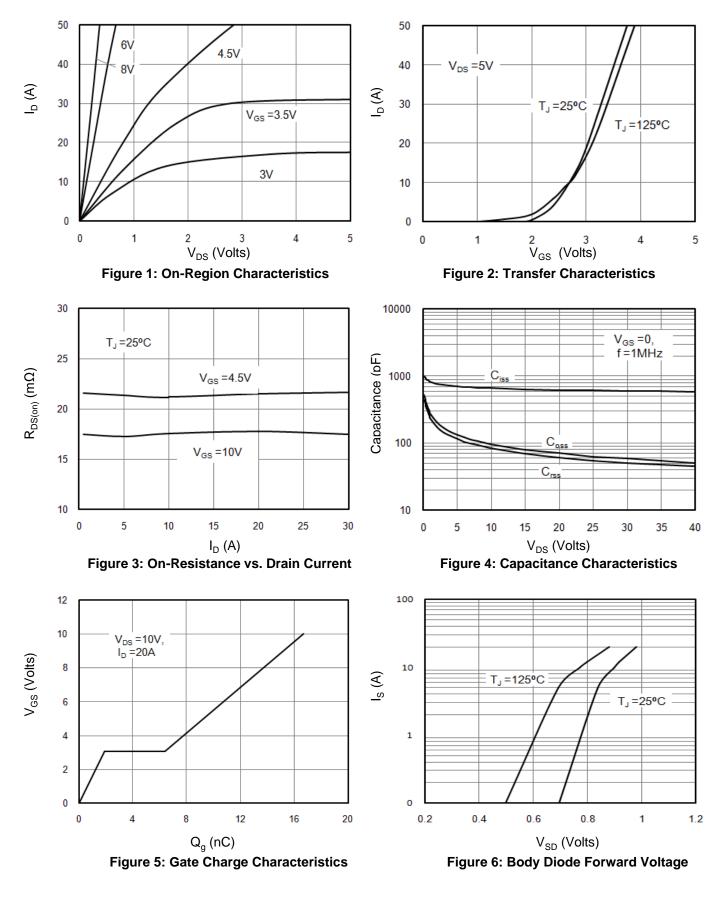
A. Single pulse width limited by maximum junction temperature.

B. The maximum current rating is package limited.

C. The power dissipation P_D is based on $T_{J(MAX)} = 175^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

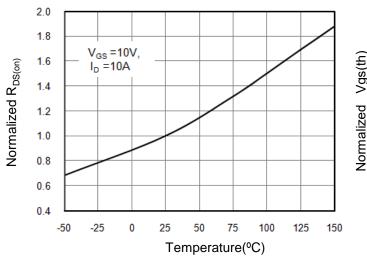


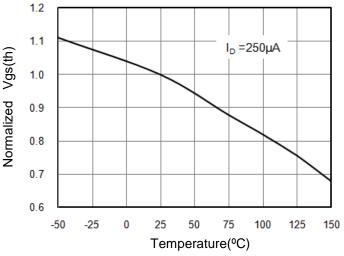
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

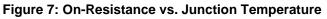


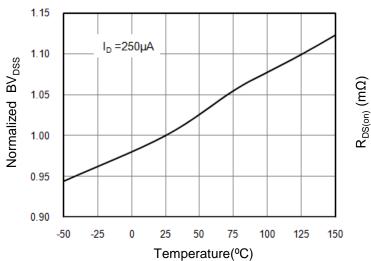


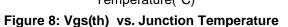
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS











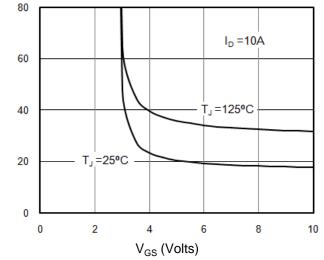


Figure 9: BV_{DSS} vs. Junction Temperature Figure 10: On-Resi

D =0.5 D =0.2

D =0.1

D =0.05

D =0.02

D =0.01

0.1

Single Pulse

Figure 10: On-Resistance vs. Gate-Source Voltage

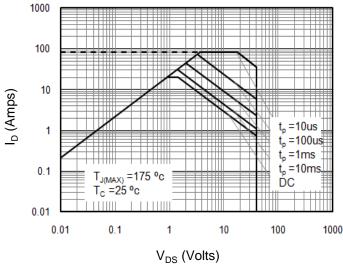


Figure 11: Normalized Transient Thermal Resistance

0.01

Figure 12: Safe Operating Area

 $Z_{\,\Theta\,JC}$ Normalized Transient Thermal Resistance

10

1

0.1

0.01

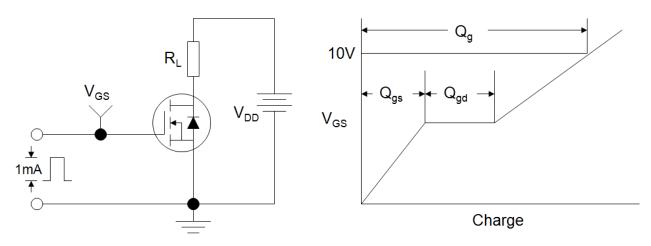
0.0001

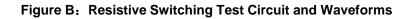
0.001

Pulse Width (s)

1







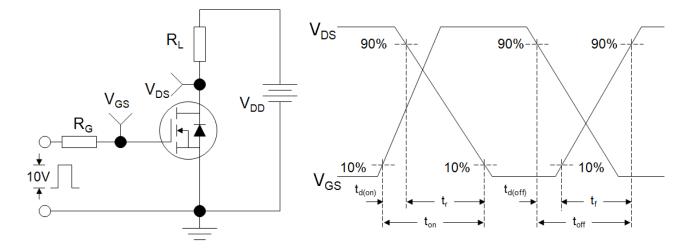
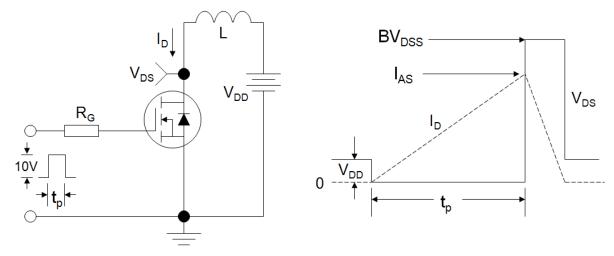
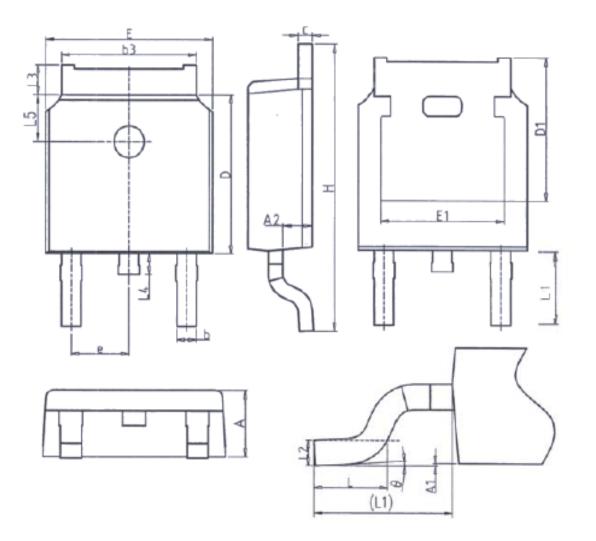


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms





TO-252(集佳)



Unit: mm					
Symbol	Min	Nom	Max		
Α	2.20	2.30	2.38		
A1	0.00	-	0.10		
A2	0.90	1.01	1.10		
b	0.72	-	0.85		
b3	5.13	5.33	5.46		
С	0.47	-	0.60		
D	6.00	6.10	6.20		
D1	5.25 REF				
E	6.50	6.60	6.70		
E1	4.70	-	-		

Unit: mm					
Symbol	Min Nom		Max		
e	2.286BSC				
Н	9.80	10.10	10.40		
L	1.40	1.50	1.70		
L1	2.90REF				
L2	0.508BSC				
L3	0.90	-	1.25		
L4	0.60	0.80	1.00		
L5	1.8 REF				
θ	0° - 8°				



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